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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	80
Number of Logic Elements/Cells	640
Total RAM Bits	-
Number of I/O	113
Number of Gates	-
Voltage - Supply	1.71V ~ 3.465V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	144-LQFP
Supplier Device Package	144-TQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lcmxo640c-4t144i

Features

- **Non-volatile, Infinitely Reconfigurable**
 - Instant-on – powers up in microseconds
 - Single chip, no external configuration memory required
 - Excellent design security, no bit stream to intercept
 - Reconfigure SRAM based logic in milliseconds
 - SRAM and non-volatile memory programmable through JTAG port
 - Supports background programming of non-volatile memory
- **Sleep Mode**
 - Allows up to 100x static current reduction
- **TransFR™ Reconfiguration (TFR)**
 - In-field logic update while system operates
- **High I/O to Logic Density**
 - 256 to 2280 LUT4s
 - 73 to 271 I/Os with extensive package options
 - Density migration supported
 - Lead free/RoHS compliant packaging
- **Embedded and Distributed Memory**
 - Up to 27.6 Kbits sysMEM™ Embedded Block RAM
 - Up to 7.7 Kbits distributed RAM
 - Dedicated FIFO control logic

- **Flexible I/O Buffer**
 - Programmable sysIO™ buffer supports wide range of interfaces:
 - LVCMOS 3.3/2.5/1.8/1.5/1.2
 - LVTTTL
 - PCI
 - LVDS, Bus-LVDS, LVPECL, RSDS
- **sysCLOCK™ PLLs**
 - Up to two analog PLLs per device
 - Clock multiply, divide, and phase shifting
- **System Level Support**
 - IEEE Standard 1149.1 Boundary Scan
 - Onboard oscillator
 - Devices operate with 3.3V, 2.5V, 1.8V or 1.2V power supply
 - IEEE 1532 compliant in-system programming

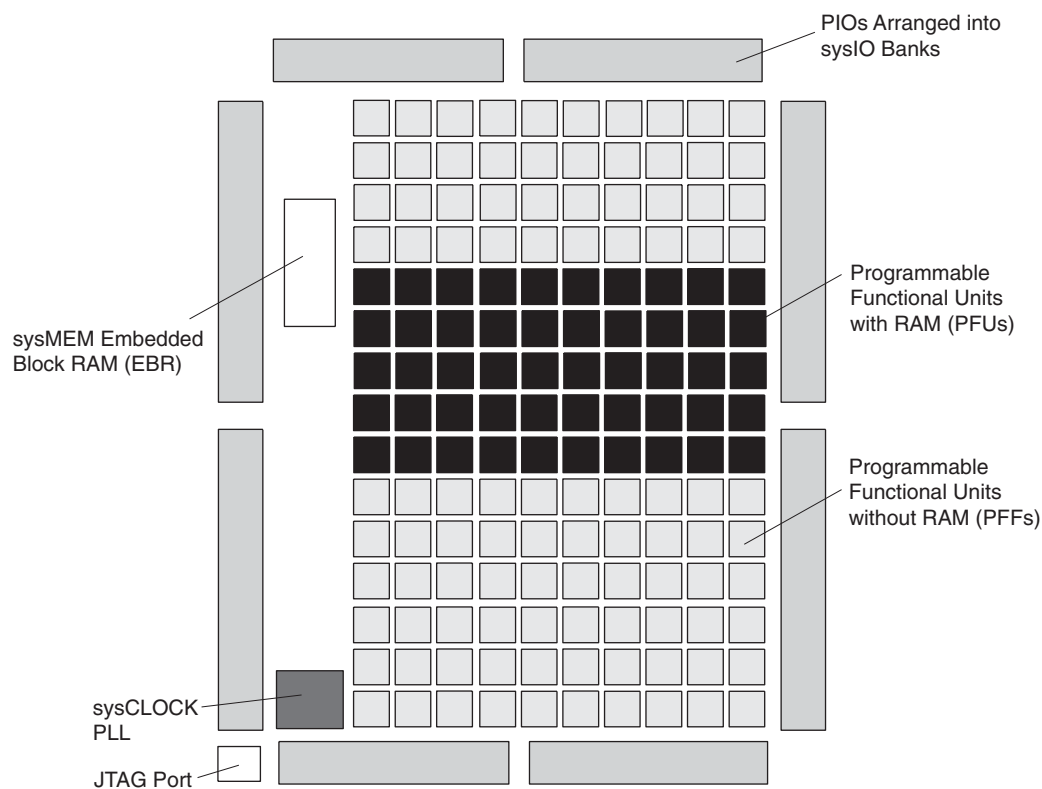
Introduction

The MachXO is optimized to meet the requirements of applications traditionally addressed by CPLDs and low capacity FPGAs: glue logic, bus bridging, bus interfacing, power-up control, and control logic. These devices bring together the best features of CPLD and FPGA devices on a single chip.

Table 1-1. MachXO Family Selection Guide

Device	LCMXO256	LCMXO640	LCMXO1200	LCMXO2280
LUTs	256	640	1200	2280
Dist. RAM (Kbits)	2.0	6.1	6.4	7.7
EBR SRAM (Kbits)	0	0	9.2	27.6
Number of EBR SRAM Blocks (9 Kbits)	0	0	1	3
V _{CC} Voltage	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V
Number of PLLs	0	0	1	2
Max. I/O	78	159	211	271
Packages				
100-pin TQFP (14x14 mm)	78	74	73	73
144-pin TQFP (20x20 mm)		113	113	113
100-ball csBGA (8x8 mm)	78	74		
132-ball csBGA (8x8 mm)		101	101	101
256-ball caBGA (14x14 mm)		159	211	211
256-ball ftBGA (17x17 mm)		159	211	211
324-ball ftBGA (19x19 mm)				271

Figure 2-1. Top View of the MachXO1200 Device¹



1. Top view of the MachXO2280 device is similar but with higher LUT count, two PLLs, and three EBR blocks.

Figure 2-2. Top View of the MachXO640 Device

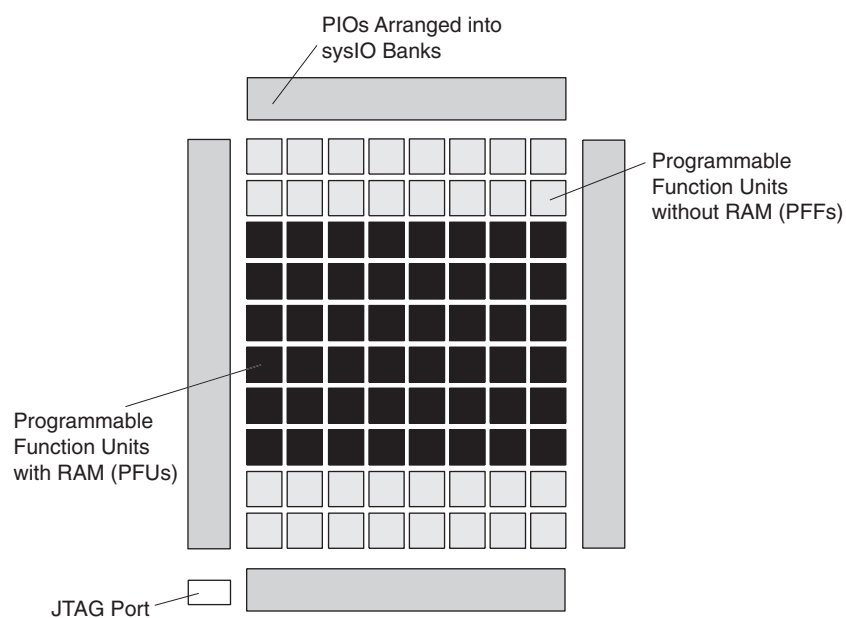
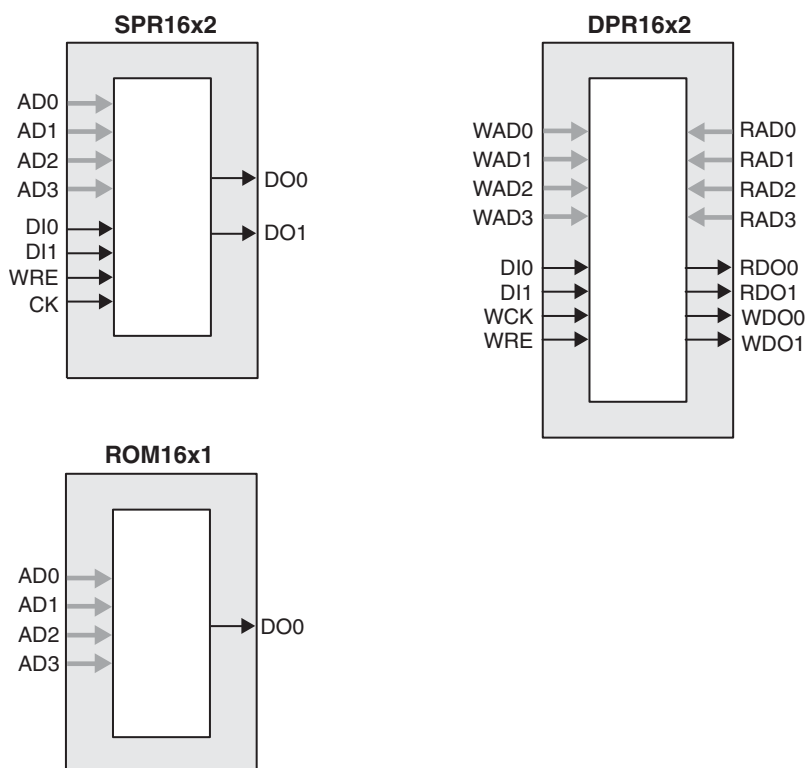


Figure 2-6. Distributed Memory Primitives



ROM Mode: The ROM mode uses the same principal as the RAM modes, but without the Write port. Pre-loading is accomplished through the programming interface during configuration.

PFU Modes of Operation

Slices can be combined within a PFU to form larger functions. Table 2-4 tabulates these modes and documents the functionality possible at the PFU level.

Table 2-4. PFU Modes of Operation

Logic	Ripple	RAM	ROM
LUT 4x8 or MUX 2x1 x 8	2-bit Add x 4	SPR16x2 x 4 DPR16x2 x 2	ROM16x1 x 8
LUT 5x4 or MUX 4x1 x 4	2-bit Sub x 4	SPR16x4 x 2 DPR16x4 x 1	ROM16x2 x 4
LUT 6x2 or MUX 8x1 x 2	2-bit Counter x 4	SPR16x8 x 1	ROM16x4 x 2
LUT 7x1 or MUX 16x1 x 1	2-bit Comp x 4		ROM16x8 x 1

Routing

There are many resources provided in the MachXO devices to route signals individually or as buses with related control signals. The routing resources consist of switching circuitry, buffers and metal interconnect (routing) segments.

The inter-PFU connections are made with three different types of routing resources: x1 (spans two PFUs), x2 (spans three PFUs) and x6 (spans seven PFUs). The x1, x2, and x6 connections provide fast and efficient connections in the horizontal and vertical directions.

sysCLOCK Phase Locked Loops (PLLs)

The MachXO1200 and MachXO2280 provide PLL support. The source of the PLL input divider can come from an external pin or from internal routing. There are four sources of feedback signals to the feedback divider: from CLKINTFB (internal feedback port), from the global clock nets, from the output of the post scalar divider, and from the routing (or from an external pin). There is a PLL_LOCK signal to indicate that the PLL has locked on to the input clock signal. Figure 2-10 shows the sysCLOCK PLL diagram.

The setup and hold times of the device can be improved by programming a delay in the feedback or input path of the PLL which will advance or delay the output clock with reference to the input clock. This delay can be either programmed during configuration or can be adjusted dynamically. In dynamic mode, the PLL may lose lock after adjustment and not relock until the t_{LOCK} parameter has been satisfied. Additionally, the phase and duty cycle block allows the user to adjust the phase and duty cycle of the CLKOS output.

The sysCLOCK PLLs provide the ability to synthesize clock frequencies. Each PLL has four dividers associated with it: input clock divider, feedback divider, post scalar divider, and secondary clock divider. The input clock divider is used to divide the input clock signal, while the feedback divider is used to multiply the input clock signal. The post scalar divider allows the VCO to operate at higher frequencies than the clock output, thereby increasing the frequency range. The secondary divider is used to derive lower frequency outputs.

Figure 2-10. PLL Diagram

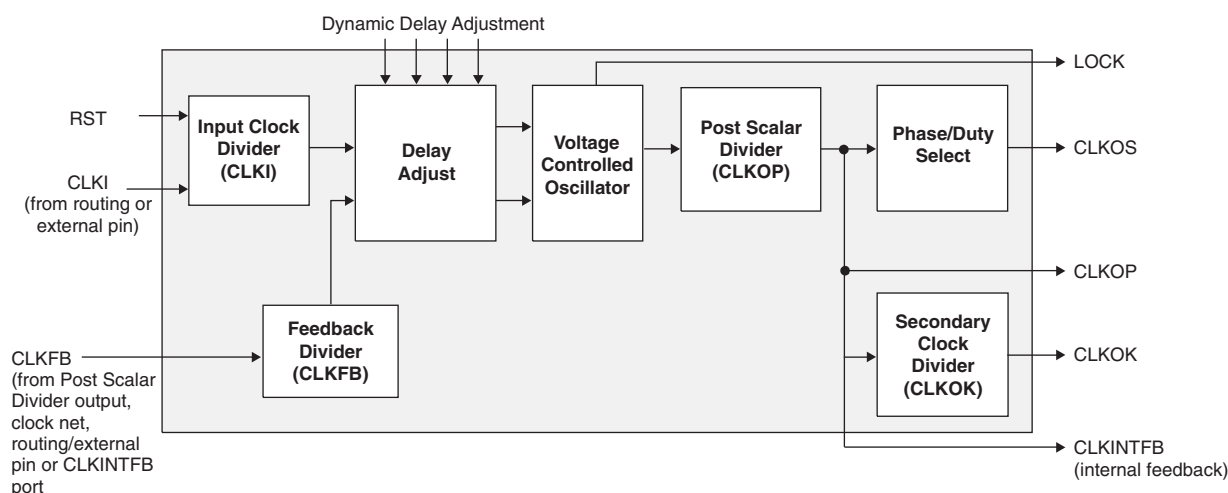
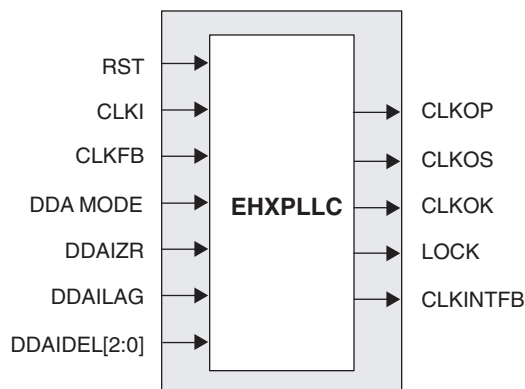


Figure 2-11 shows the available macros for the PLL. Table 2-5 provides signal description of the PLL Block.

Figure 2-11. PLL Primitive



The EBR memory supports three forms of write behavior for single or dual port operation:

1. **Normal** – data on the output appears only during the read cycle. During a write cycle, the data (at the current address) does not appear on the output. This mode is supported for all data widths.
2. **Write Through** – a copy of the input data appears at the output of the same port. This mode is supported for all data widths.
3. **Read-Before-Write** – when new data is being written, the old contents of the address appears at the output. This mode is supported for x9, x18 and x36 data widths.

FIFO Configuration

The FIFO has a write port with Data-in, CEW, WE and CLKW signals. There is a separate read port with Data-out, RCE, RE and CLKR signals. The FIFO internally generates Almost Full, Full, Almost Empty and Empty Flags. The Full and Almost Full flags are registered with CLKW. The Empty and Almost Empty flags are registered with CLKR. The range of programming values for these flags are in Table 2-7.

Table 2-7. Programmable FIFO Flag Ranges

Flag Name	Programming Range
Full (FF)	1 to (up to 2^N-1)
Almost Full (AF)	1 to Full-1
Almost Empty (AE)	1 to Full-1
Empty (EF)	0

N = Address bit width

The FIFO state machine supports two types of reset signals: RSTA and RSTB. The RSTA signal is a global reset that clears the contents of the FIFO by resetting the read/write pointer and puts the FIFO flags in their initial reset state. The RSTB signal is used to reset the read pointer. The purpose of this reset is to retransmit the data that is in the FIFO. In these applications it is important to keep careful track of when a packet is written into or read from the FIFO.

Memory Core Reset

The memory array in the EBR utilizes latches at the A and B output ports. These latches can be reset asynchronously. RSTA and RSTB are local signals, which reset the output latches associated with Port A and Port B respectively. The Global Reset (GSRN) signal resets both ports. The output data latches and associated resets for both ports are as shown in Figure 2-13.

Table 2-10. Supported Output Standards

Output Standard	Drive	V _{CCIO} (Typ.)
Single-ended Interfaces		
LVTTTL	4mA, 8mA, 12mA, 16mA	3.3
LVC MOS33	4mA, 8mA, 12mA, 14mA	3.3
LVC MOS25	4mA, 8mA, 12mA, 14mA	2.5
LVC MOS18	4mA, 8mA, 12mA, 14mA	1.8
LVC MOS15	4mA, 8mA	1.5
LVC MOS12	2mA, 6mA	1.2
LVC MOS33, Open Drain	4mA, 8mA, 12mA, 14mA	—
LVC MOS25, Open Drain	4mA, 8mA, 12mA, 14mA	—
LVC MOS18, Open Drain	4mA, 8mA, 12mA, 14mA	—
LVC MOS15, Open Drain	4mA, 8mA	—
LVC MOS12, Open Drain	2mA, 6mA	—
PCI33 ³	N/A	3.3
Differential Interfaces		
LVDS ^{1, 2}	N/A	2.5
BLVDS, RSDS ²	N/A	2.5
LVPECL ²	N/A	3.3

1. MachXO1200 and MachXO2280 devices have dedicated LVDS buffers.

2. These interfaces can be emulated with external resistors in all devices.

3. Top Banks of MachXO1200 and MachXO2280 devices only.

sysIO Buffer Banks

The number of Banks vary between the devices of this family. Eight Banks surround the two larger devices, the MachXO1200 and MachXO2280 (two Banks per side). The MachXO640 has four Banks (one Bank per side). The smallest member of this family, the MachXO256, has only two Banks.

Each sysIO buffer Bank is capable of supporting multiple I/O standards. Each Bank has its own I/O supply voltage (V_{CCIO}) which allows it to be completely independent from the other Banks. Figure 2-18, Figure 2-18, Figure 2-20 and Figure 2-21 shows the sysIO Banks and their associated supplies for all devices.

Figure 2-18. MachXO2280 Banks

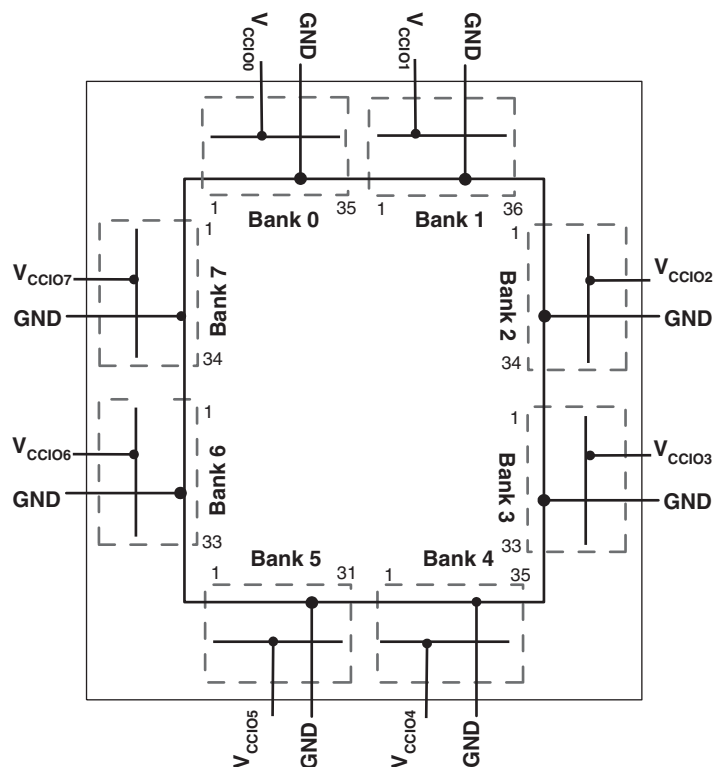


Figure 2-19. MachXO1200 Banks

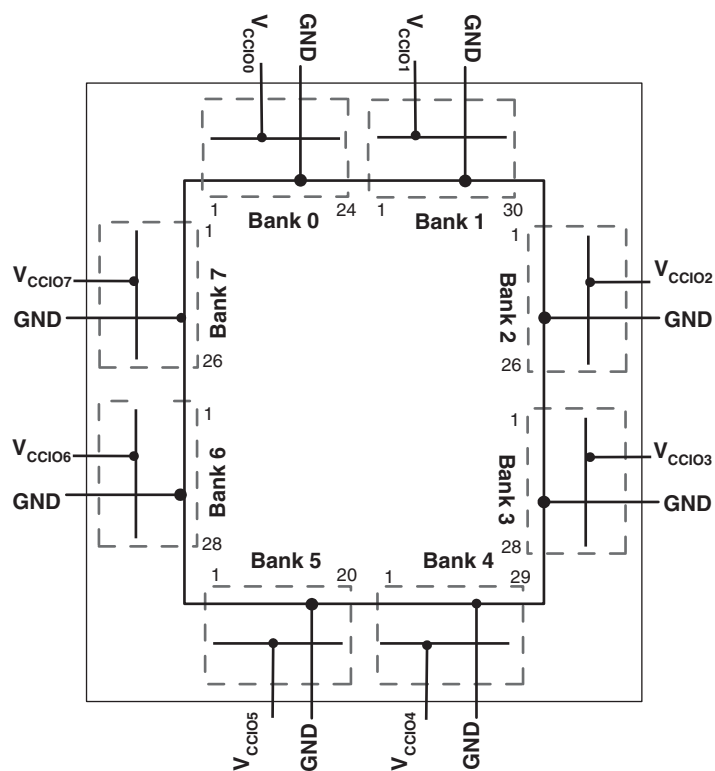


Figure 2-20. MachXO640 Banks

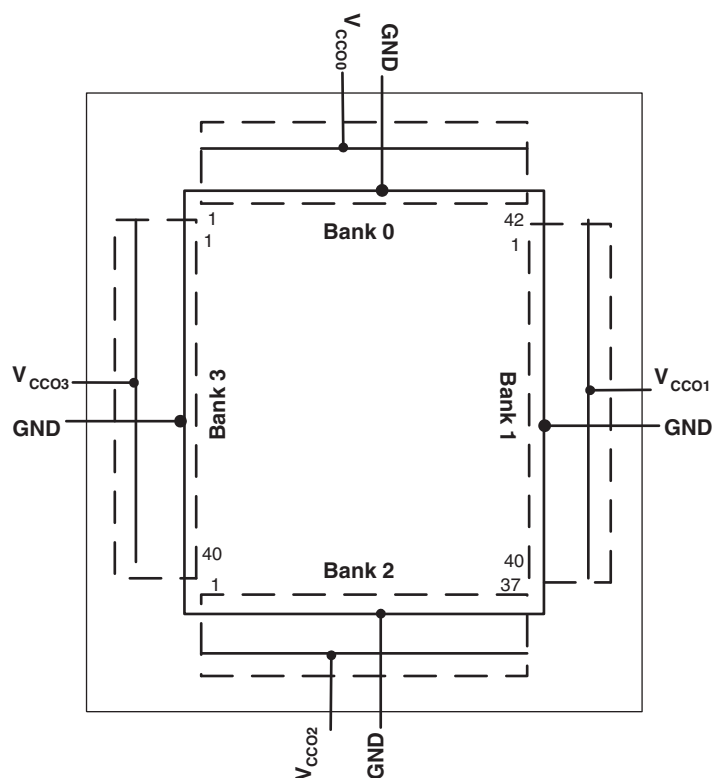
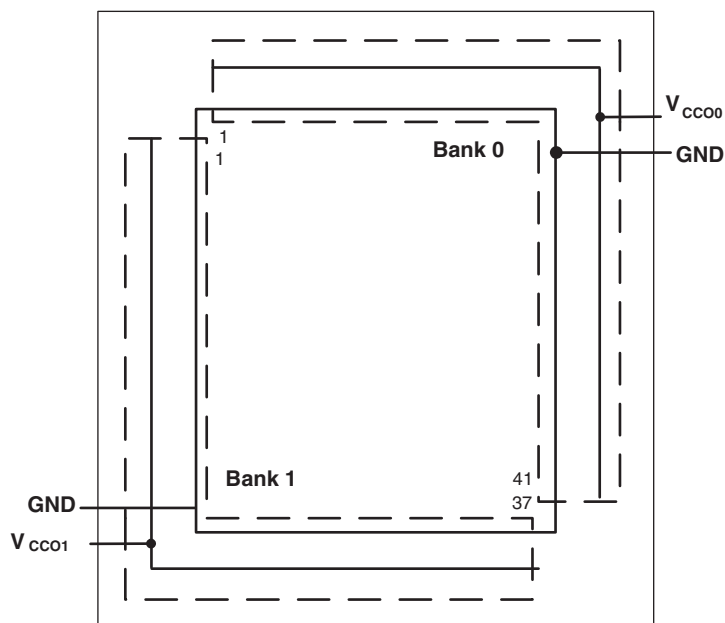


Figure 2-21. MachXO256 Banks



Hot Socketing

The MachXO devices have been carefully designed to ensure predictable behavior during power-up and power-down. Leakage into I/O pins is controlled to within specified limits. This allows for easy integration with the rest of

Table 3-2. BLVDS DC Conditions¹

Over Recommended Operating Conditions

Symbol	Description	Nominal		Units
		Z _o = 45	Z _o = 90	
Z _{OUT}	Output impedance	100	100	Ohms
R _{TLEFT}	Left end termination	45	90	Ohms
R _{TRIGHT}	Right end termination	45	90	Ohms
V _{OH}	Output high voltage	1.375	1.48	V
V _{OL}	Output low voltage	1.125	1.02	V
V _{OD}	Output differential voltage	0.25	0.46	V
V _{CM}	Output common mode voltage	1.25	1.25	V
I _{DC}	DC output current	11.2	10.2	mA

1. For input buffer, see LVDS table.

LVPECL

The MachXO family supports the differential LVPECL standard through emulation. This output standard is emulated using complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs on all the devices. The LVPECL input standard is supported by the LVDS differential input buffer on certain devices. The scheme shown in Figure 3-3 is one possible solution for point-to-point signals.

Figure 3-3. Differential LVPECL

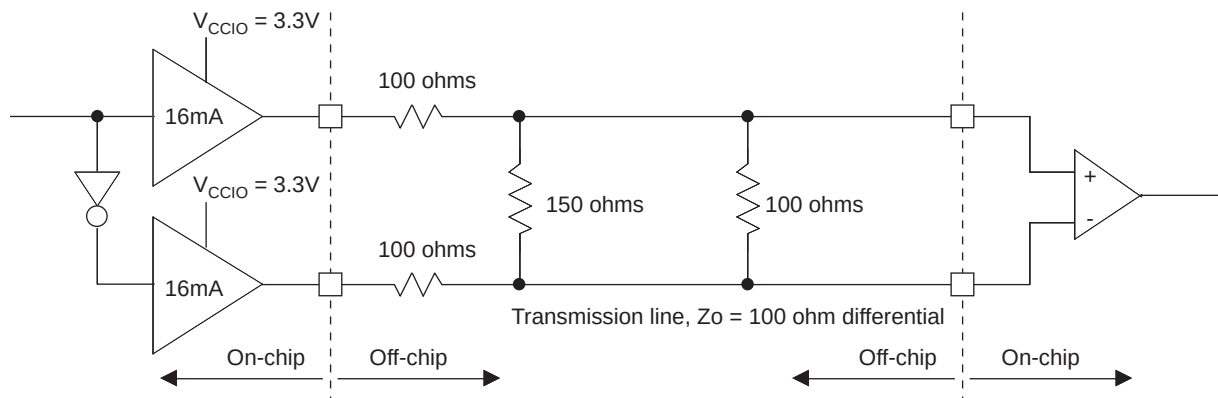


Table 3-3. LVPECL DC Conditions¹

Over Recommended Operating Conditions

Symbol	Description	Nominal	Units
Z _{OUT}	Output impedance	100	Ohms
R _P	Driver parallel resistor	150	Ohms
R _T	Receiver termination	100	Ohms
V _{OH}	Output high voltage	2.03	V
V _{OL}	Output low voltage	1.27	V
V _{OD}	Output differential voltage	0.76	V
V _{CM}	Output common mode voltage	1.65	V
Z _{BACK}	Back impedance	85.7	Ohms
I _{DC}	DC output current	12.7	mA

1. For input buffer, see LVDS table.

For further information on LVPECL, BLVDS and other differential interfaces please see details of additional technical documentation at the end of the data sheet.

RSDS

The MachXO family supports the differential RSDS standard. The output standard is emulated using complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs on all the devices. The RSDS input standard is supported by the LVDS differential input buffer on certain devices. The scheme shown in Figure 3-4 is one possible solution for RSDS standard implementation. Use LVDS25E mode with suggested resistors for RSDS operation. Resistor values in Figure 3-4 are industry standard values for 1% resistors.

Figure 3-4. RSDS (Reduced Swing Differential Standard)

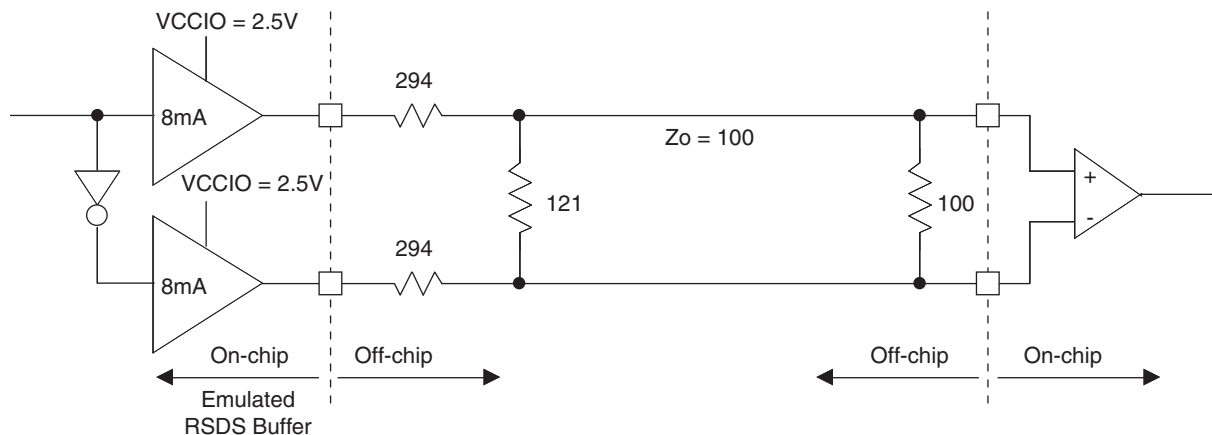


Table 3-4. RSDS DC Conditions

Parameter	Description	Typical	Units
Z_{OUT}	Output impedance	20	Ohms
R_S	Driver series resistor	294	Ohms
R_P	Driver parallel resistor	121	Ohms
R_T	Receiver termination	100	Ohms
V_{OH}	Output high voltage	1.35	V
V_{OL}	Output low voltage	1.15	V
V_{OD}	Output differential voltage	0.20	V
V_{CM}	Output common mode voltage	1.25	V
Z_{BACK}	Back impedance	101.5	Ohms
I_{DC}	DC output current	3.66	mA

MachXO Internal Timing Parameters¹

Over Recommended Operating Conditions

Parameter	Description	-5		-4		-3		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
PFU/PFF Logic Mode Timing								
t _{LUT4_PFU}	LUT4 delay (A to D inputs to F output)	—	0.28	—	0.34	—	0.39	ns
t _{LUT6_PFU}	LUT6 delay (A to D inputs to OFX output)	—	0.44	—	0.53	—	0.62	ns
t _{LSR_PFU}	Set/Reset to output of PFU	—	0.90	—	1.08	—	1.26	ns
t _{SUM_PFU}	Clock to Mux (M0,M1) input setup time	0.10	—	0.13	—	0.15	—	ns
t _{HM_PFU}	Clock to Mux (M0,M1) input hold time	-0.05	—	-0.06	—	-0.07	—	ns
t _{SUD_PFU}	Clock to D input setup time	0.13	—	0.16	—	0.18	—	ns
t _{HD_PFU}	Clock to D input hold time	-0.03	—	-0.03	—	-0.04	—	ns
t _{CK2Q_PFU}	Clock to Q delay, D-type register configuration	—	0.40	—	0.48	—	0.56	ns
t _{LE2Q_PFU}	Clock to Q delay latch configuration	—	0.53	—	0.64	—	0.74	ns
t _{LD2Q_PFU}	D to Q throughput delay when latch is enabled	—	0.55	—	0.66	—	0.77	ns
PFU Dual Port Memory Mode Timing								
t _{CORAM_PFU}	Clock to Output	—	0.40	—	0.48	—	0.56	ns
t _{SUDATA_PFU}	Data Setup Time	-0.18	—	-0.22	—	-0.25	—	ns
t _{HDATA_PFU}	Data Hold Time	0.28	—	0.34	—	0.39	—	ns
t _{SUADDR_PFU}	Address Setup Time	-0.46	—	-0.56	—	-0.65	—	ns
t _{HADDR_PFU}	Address Hold Time	0.71	—	0.85	—	0.99	—	ns
t _{SUWREN_PFU}	Write/Read Enable Setup Time	-0.22	—	-0.26	—	-0.30	—	ns
t _{HWREN_PFU}	Write/Read Enable Hold Time	0.33	—	0.40	—	0.47	—	ns
PIO Input/Output Buffer Timing								
t _{IN_PIO}	Input Buffer Delay	—	0.75	—	0.90	—	1.06	ns
t _{OUT_PIO}	Output Buffer Delay	—	1.29	—	1.54	—	1.80	ns
EBR Timing (1200 and 2280 Devices Only)								
t _{CO_EBR}	Clock to output from Address or Data with no output register	—	2.24	—	2.69	—	3.14	ns
t _{COO_EBR}	Clock to output from EBR output Register	—	0.54	—	0.64	—	0.75	ns
t _{SUDATA_EBR}	Setup Data to EBR Memory	-0.26	—	-0.31	—	-0.37	—	ns
t _{HDATA_EBR}	Hold Data to EBR Memory	0.41	—	0.49	—	0.57	—	ns
t _{SUADDR_EBR}	Setup Address to EBR Memory	-0.26	—	-0.31	—	-0.37	—	ns
t _{HADDR_EBR}	Hold Address to EBR Memory	0.41	—	0.49	—	0.57	—	ns
t _{SUWREN_EBR}	Setup Write/Read Enable to EBR Memory	-0.17	—	-0.20	—	-0.23	—	ns
t _{HWREN_EBR}	Hold Write/Read Enable to EBR Memory	0.26	—	0.31	—	0.36	—	ns
t _{SUCE_EBR}	Clock Enable Setup Time to EBR Output Register	0.19	—	0.23	—	0.27	—	ns
t _{HCE_EBR}	Clock Enable Hold Time to EBR Output Register	-0.13	—	-0.16	—	-0.18	—	ns
t _{RSTO_EBR}	Reset To Output Delay Time from EBR Output Register	—	1.03	—	1.23	—	1.44	ns
PLL Parameters (1200 and 2280 Devices Only)								
t _{RSTREC}	Reset Recovery to Rising Clock	1.00	—	1.00	—	1.00	—	ns
t _{RSTSU}	Reset Signal Setup Time	1.00	—	1.00	—	1.00	—	ns

1. Internal parameters are characterized but not tested on every device.

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MachXO Family Timing Adders^{1, 2, 3}

Over Recommended Operating Conditions

Buffer Type	Description	-5	-4	-3	Units
Input Adjusters					
LVDS25 ⁴	LVDS	0.44	0.53	0.61	ns
BLVDS25 ⁴	BLVDS	0.44	0.53	0.61	ns
LVPECL33 ⁴	LVPECL	0.42	0.50	0.59	ns
LVTTTL33	LVTTTL	0.01	0.01	0.01	ns
LVC MOS33	LVC MOS 3.3	0.01	0.01	0.01	ns
LVC MOS25	LVC MOS 2.5	0.00	0.00	0.00	ns
LVC MOS18	LVC MOS 1.8	0.07	0.08	0.10	ns
LVC MOS15	LVC MOS 1.5	0.14	0.17	0.19	ns
LVC MOS12	LVC MOS 1.2	0.40	0.48	0.56	ns
PCI33 ⁴	PCI	0.01	0.01	0.01	ns
Output Adjusters					
LVDS25E	LVDS 2.5 E	-0.13	-0.15	-0.18	ns
LVDS25 ⁴	LVDS 2.5	-0.21	-0.26	-0.30	ns
BLVDS25	BLVDS 2.5	-0.03	-0.03	-0.04	ns
LVPECL33	LVPECL 3.3	0.04	0.04	0.05	ns
LVTTTL33_4mA	LVTTTL 4mA drive	0.04	0.04	0.05	ns
LVTTTL33_8mA	LVTTTL 8mA drive	0.06	0.07	0.08	ns
LVTTTL33_12mA	LVTTTL 12mA drive	-0.01	-0.01	-0.01	ns
LVTTTL33_16mA	LVTTTL 16mA drive	0.50	0.60	0.70	ns
LVC MOS33_4mA	LVC MOS 3.3 4mA drive	0.04	0.04	0.05	ns
LVC MOS33_8mA	LVC MOS 3.3 8mA drive	0.06	0.07	0.08	ns
LVC MOS33_12mA	LVC MOS 3.3 12mA drive	-0.01	-0.01	-0.01	ns
LVC MOS33_14mA	LVC MOS 3.3 14mA drive	0.50	0.60	0.70	ns
LVC MOS25_4mA	LVC MOS 2.5 4mA drive	0.05	0.06	0.07	ns
LVC MOS25_8mA	LVC MOS 2.5 8mA drive	0.10	0.12	0.13	ns
LVC MOS25_12mA	LVC MOS 2.5 12mA drive	0.00	0.00	0.00	ns
LVC MOS25_14mA	LVC MOS 2.5 14mA drive	0.34	0.40	0.47	ns
LVC MOS18_4mA	LVC MOS 1.8 4mA drive	0.11	0.13	0.15	ns
LVC MOS18_8mA	LVC MOS 1.8 8mA drive	0.05	0.06	0.06	ns
LVC MOS18_12mA	LVC MOS 1.8 12mA drive	-0.06	-0.07	-0.08	ns
LVC MOS18_14mA	LVC MOS 1.8 14mA drive	0.06	0.07	0.09	ns
LVC MOS15_4mA	LVC MOS 1.5 4mA drive	0.15	0.19	0.22	ns
LVC MOS15_8mA	LVC MOS 1.5 8mA drive	0.05	0.06	0.07	ns
LVC MOS12_2mA	LVC MOS 1.2 2mA drive	0.26	0.31	0.36	ns
LVC MOS12_6mA	LVC MOS 1.2 6mA drive	0.05	0.06	0.07	ns
PCI33 ⁴	PCI33	1.85	2.22	2.59	ns

1. Timing adders are characterized but not tested on every device.

2. LVC MOS timing is measured with the load specified in Switching Test Conditions table.

3. All other standards tested according to the appropriate specifications.

4. I/O standard only available in LCMXO1200 and LCMXO2280 devices.

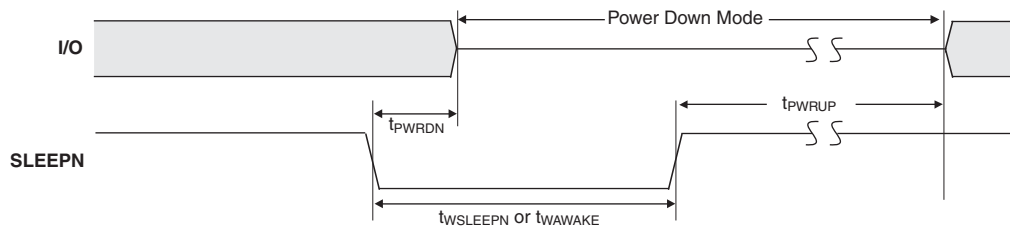
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MachXO “C” Sleep Mode Timing

Symbol	Parameter	Device	Min.	Typ.	Max	Units
t_{PWRDN}	SLEEPN Low to Power Down	All	—	—	400	ns
t_{PWRUP}	SLEEPN High to Power Up	LCMXO256	—	—	400	μs
		LCMXO640	—	—	600	μs
		LCMXO1200	—	—	800	μs
		LCMXO2280	—	—	1000	μs
$t_{WSLEEPN}$	SLEEPN Pulse Width	All	400	—	—	ns
t_{WAWAKE}	SLEEPN Pulse Rejection	All	—	—	100	ns

Rev. A 0.19

Flash Download Time



Symbol	Parameter	Min.	Typ.	Max.	Units
$t_{REFRESH}$	Minimum V_{CC} or V_{CCAUX} (later of the two supplies) to Device I/O Active	LCMXO256	—	0.4	ms
		LCMXO640	—	0.6	ms
		LCMXO1200	—	0.8	ms
		LCMXO2280	—	1.0	ms

JTAG Port Timing Specifications

Symbol	Parameter	Min.	Max.	Units
f_{MAX}	TCK [BSCAN] clock frequency	—	25	MHz
t_{BTCP}	TCK [BSCAN] clock pulse width	40	—	ns
t_{BTCPH}	TCK [BSCAN] clock pulse width high	20	—	ns
t_{BTCPL}	TCK [BSCAN] clock pulse width low	20	—	ns
t_{BTS}	TCK [BSCAN] setup time	8	—	ns
t_{BTH}	TCK [BSCAN] hold time	10	—	ns
t_{BTRF}	TCK [BSCAN] rise/fall time	50	—	mV/ns
t_{BTCO}	TAP controller falling edge of clock to output valid	—	10	ns
$t_{BTCODIS}$	TAP controller falling edge of clock to output disabled	—	10	ns
t_{BTCOEN}	TAP controller falling edge of clock to output enabled	—	10	ns
t_{BTCRS}	BSCAN test capture register setup time	8	—	ns
t_{BTCRH}	BSCAN test capture register hold time	25	—	ns
t_{BUTCO}	BSCAN test update register, falling edge of clock to output valid	—	25	ns
$t_{BTUODIS}$	BSCAN test update register, falling edge of clock to output disabled	—	25	ns
$t_{BTUPOEN}$	BSCAN test update register, falling edge of clock to output enabled	—	25	ns

Rev. A 0.19

LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections: 144 TQFP

Pin Number	LCMXO640				LCMXO1200				LCMXO2280			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
1	PL2A	3		T	PL2A	7		T	PL2A	7	LUM0_PLLT_FB_A	T
2	PL2C	3		T	PL2B	7		C	PL2B	7	LUM0_PLLC_FB_A	C
3	PL2B	3		C	PL3A	7		T*	PL3A	7		T*
4	PL3A	3		T	PL3B	7		C*	PL3B	7		C*
5	PL2D	3		C	PL3C	7		T	PL3C	7	LUM0_PLLT_IN_A	T
6	PL3B	3		C	PL3D	7		C	PL3D	7	LUM0_PLLC_IN_A	C
7	PL3C	3		T	PL4A	7		T*	PL4A	7		T*
8	PL3D	3		C	PL4B	7		C*	PL4B	7		C*
9	PL4A	3			PL4C	7			PL4C	7		
10	VCCIO3	3			VCCIO7	7			VCCIO7	7		
11	GNDIO3	3			GNDIO7	7			GNDIO7	7		
12	PL4D	3			PL5C	7			PL6C	7		
13	PL5A	3		T	PL6A	7		T*	PL7A	7		T*
14	PL5B	3	GSRN	C	PL6B	7	GSRN	C*	PL7B	7	GSRN	C*
15	PL5D	3			PL6D	7			PL7D	7		
16	GND	-			GND	-			GND	-		
17	PL6C	3		T	PL7C	7		T	PL9C	7		T
18	PL6D	3		C	PL7D	7		C	PL9D	7		C
19	PL7A	3		T	PL10A	6		T*	PL13A	6		T*
20	PL7B	3		C	PL10B	6		C*	PL13B	6		C*
21	VCC	-			VCC	-			VCC	-		
22	PL8A	3		T	PL11A	6		T*	PL13D	6		
23	PL8B	3		C	PL11B	6		C*	PL14D	6		C
24	PL8C	3	TSALL		PL11C	6	TSALL		PL14C	6	TSALL	T
25	PL9C	3		T	PL12B	6			PL15B	6		
26	VCCIO3	3			VCCIO6	6			VCCIO6	6		
27	GNDIO3	3			GNDIO6	6			GNDIO6	6		
28	PL9D	3		C	PL13D	6			PL16D	6		
29	PL10A	3		T	PL14A	6	LLM0_PLLT_FB_A	T*	PL17A	6	LLM0_PLLT_FB_A	T*
30	PL10B	3		C	PL14B	6	LLM0_PLLC_FB_A	C*	PL17B	6	LLM0_PLLC_FB_A	C*
31	PL10C	3		T	PL14C	6		T	PL17C	6		T
32	PL11A	3		T	PL14D	6		C	PL17D	6		C
33	PL10D	3		C	PL15A	6	LLM0_PLLT_IN_A	T*	PL18A	6	LLM0_PLLT_IN_A	T*
34	PL11C	3		T	PL15B	6	LLM0_PLLC_IN_A	C*	PL18B	6	LLM0_PLLC_IN_A	C*
35	PL11B	3		C	PL16A	6		T	PL19A	6		T
36	PL11D	3		C	PL16B	6		C	PL19B	6		C
37	GNDIO2	2			GNDIO5	5			GNDIO5	5		
38	VCCIO2	2			VCCIO5	5			VCCIO5	5		
39	TMS	2	TMS		TMS	5	TMS		TMS	5	TMS	
40	PB2C	2			PB2C	5		T	PB2A	5		T
41	PB3A	2		T	PB2D	5		C	PB2B	5		C
42	TCK	2	TCK		TCK	5	TCK		TCK	5	TCK	
43	PB3B	2		C	PB3A	5		T	PB3A	5		T
44	PB3C	2		T	PB3B	5		C	PB3B	5		C
45	PB3D	2		C	PB4A	5		T	PB4A	5		T
46	PB4A	2		T	PB4B	5		C	PB4B	5		C
47	TDO	2	TDO		TDO	5	TDO		TDO	5	TDO	
48	PB4B	2		C	PB4D	5			PB4D	5		
49	PB4C	2		T	PB5A	5		T	PB5A	5		T
50	PB4D	2		C	PB5B	5		C	PB5B	5		C

LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections: 256 caBGA / 256 ftBGA (Cont.)

LCMXO640					LCMXO1200					LCMXO2280				
Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential
J4	PL8A	3		T	J4	PL13A	6		T*	J4	PL16A	6		T*
J5	PL8B	3		C	J5	PL13B	6		C*	J5	PL16B	6		C*
R1	PL11A	3		T	R1	PL13C	6		T	R1	PL16C	6		T
R2	PL11B	3		C	R2	PL13D	6		C	R2	PL16D	6		C
-	-	-			-	-	-			GND	GND	-		
K5	NC				K5	PL14A	6	LLM0_PLLT_FB_A	T*	K5	PL17A	6	LLM0_PLLT_FB_A	T*
K4	NC				K4	PL14B	6	LLM0_PLLC_FB_A	C*	K4	PL17B	6	LLM0_PLLC_FB_A	C*
L5	PL10C	3		T	L5	PL14C	6		T	L5	PL17C	6		T
L4	PL10D	3		C	L4	PL14D	6		C	L4	PL17D	6		C
M5	NC				M5	PL15A	6	LLM0_PLLT_IN_A	T*	M5	PL18A	6	LLM0_PLLT_IN_A	T*
M4	NC				M4	PL15B	6	LLM0_PLLC_IN_A	C*	M4	PL18B	6	LLM0_PLLC_IN_A	C*
N4	PL11C	3		T	N4	PL16A	6		T	N4	PL19A	6		T
N3	PL11D	3		C	N3	PL16B	6		C	N3	PL19B	6		C
VCCIO3	VCCIO3	3			VCCIO6	VCCIO6	6			VCCIO6	VCCIO6	6		
GND	GNDIO3	3			GND	GNDIO6	6			GND	GNDIO6	6		
GND	GNDIO2	2			GND	GNDIO5	5			GND	GNDIO5	5		
VCCIO2	VCCIO2	2			VCCIO5	VCCIO5	5			VCCIO5	VCCIO5	5		
P4	TMS	2	TMS		P4	TMS	5	TMS		P4	TMS	5	TMS	
P2	NC				P2	PB2A	5		T	P2	PB2A	5		T
P3	NC				P3	PB2B	5		C	P3	PB2B	5		C
N5	NC				N5	PB2C	5		T	N5	PB2C	5		T
R3	TCK	2	TCK		R3	TCK	5	TCK		R3	TCK	5	TCK	
N6	NC				N6	PB2D	5		C	N6	PB2D	5		C
T2	PB2A	2		T	T2	PB3A	5		T	T2	PB3A	5		T
T3	PB2B	2		C	T3	PB3B	5		C	T3	PB3B	5		C
R4	PB2C	2		T	R4	PB3C	5		T	R4	PB3C	5		T
R5	PB2D	2		C	R5	PB3D	5		C	R5	PB3D	5		C
P5	PB3A	2		T	P5	PB4A	5		T	P5	PB4A	5		T
P6	PB3B	2		C	P6	PB4B	5		C	P6	PB4B	5		C
T5	PB3C	2		T	T5	PB4C	5		T	T5	PB4C	5		T
M6	TDO	2	TDO		M6	TDO	5	TDO		M6	TDO	5	TDO	
T4	PB3D	2		C	T4	PB4D	5		C	T4	PB4D	5		C
R6	PB4A	2		T	R6	PB5A	5		T	R6	PB5A	5		T
GND	GNDIO2	2			GND	GNDIO5	5			GND	GNDIO5	5		
VCCIO2	VCCIO2	2			VCCIO5	VCCIO5	5			VCCIO5	VCCIO5	5		
T6	PB4B	2		C	T6	PB5B	5		C	T6	PB5B	5		C
N7	TDI	2	TDI		N7	TDI	5	TDI		N7	TDI	5	TDI	
T8	PB4C	2		T	T8	PB5C	5		T	T8	PB6A	5		T
T7	PB4D	2		C	T7	PB5D	5		C	T7	PB6B	5		C
M7	NC				M7	PB6A	5		T	M7	PB7C	5		T
M8	NC				M8	PB6B	5		C	M8	PB7D	5		C
T9	VCCAUX	-			T9	VCCAUX	-			T9	VCCAUX	-		
R7	PB4E	2		T	R7	PB6C	5		T	R7	PB8C	5		T
R8	PB4F	2		C	R8	PB6D	5		C	R8	PB8D	5		C
-	-				VCCIO5	VCCIO5	5			VCCIO5	VCCIO5	5		
-	-				GND	GNDIO5	5			GND	GNDIO5	5		
P7	PB5C	2		T	P7	PB6E	5		T	P7	PB9A	4		T
P8	PB5D	2		C	P8	PB6F	5		C	P8	PB9B	4		C
N8	PB5A	2		T	N8	PB7A	4		T	N8	PB10E	4		T
N9	PB5B	2	PCLK2_1***	C	N9	PB7B	4	PCLK4_1***	C	N9	PB10F	4	PCLK4_1***	C
P10	PB7B	2		C	P10	PB7D	4		C	P10	PB10D	4		C
P9	PB7A	2		T	P9	PB7C	4		T	P9	PB10C	4		T
M9	PB6B	2	PCLK2_0***	C	M9	PB7F	4	PCLK4_0***	C	M9	PB10B	4	PCLK4_0***	C

LCMX02280 Logic Signal Connections: 324 ftBGA (Cont.)

LCMX02280				
Ball Number	Ball Function	Bank	Dual Function	Differential
A10	PT8E	0		T
VCCIO0	VCCIO0	0		
GND	GNDIO0	0		
A9	PT8D	0		C
C9	PT8C	0		T
B9	PT8B	0		C
F9	VCCAUX	-		
A8	PT8A	0		T
B8	PT7D	0		C
C8	PT7C	0		T
VCC	VCC	-		
A7	PT7B	0		C
B7	PT7A	0		T
A6	PT6A	0		T
B6	PT6B	0		C
D8	PT6C	0		T
F8	PT6D	0		C
C7	PT6E	0		T
E8	PT6F	0		C
D7	PT5D	0		C
VCCIO0	VCCIO0	0		
GND	GNDIO0	0		
E7	PT5C	0		T
A5	PT5B	0		C
C6	PT5A	0		T
B5	PT4A	0		T
A4	PT4B	0		C
D6	PT4C	0		T
F7	PT4D	0		C
B4	PT4E	0		T
GND	GND	-		
C5	PT4F	0		C
F6	PT3D	0		C
E5	PT3C	0		T
E6	PT3B	0		C
D5	PT3A	0		T
A3	PT2D	0		C
C4	PT2C	0		T
A2	PT2B	0		C
B2	PT2A	0		T
VCCIO0	VCCIO0	0		
GND	GNDIO0	0		
E14	GND	-		

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO2280C-3T100C	2280	1.8V/2.5V/3.3V	73	-3	TQFP	100	COM
LCMXO2280C-4T100C	2280	1.8V/2.5V/3.3V	73	-4	TQFP	100	COM
LCMXO2280C-5T100C	2280	1.8V/2.5V/3.3V	73	-5	TQFP	100	COM
LCMXO2280C-3T144C	2280	1.8V/2.5V/3.3V	113	-3	TQFP	144	COM
LCMXO2280C-4T144C	2280	1.8V/2.5V/3.3V	113	-4	TQFP	144	COM
LCMXO2280C-5T144C	2280	1.8V/2.5V/3.3V	113	-5	TQFP	144	COM
LCMXO2280C-3M132C	2280	1.8V/2.5V/3.3V	101	-3	csBGA	132	COM
LCMXO2280C-4M132C	2280	1.8V/2.5V/3.3V	101	-4	csBGA	132	COM
LCMXO2280C-5M132C	2280	1.8V/2.5V/3.3V	101	-5	csBGA	132	COM
LCMXO2280C-3B256C	2280	1.8V/2.5V/3.3V	211	-3	caBGA	256	COM
LCMXO2280C-4B256C	2280	1.8V/2.5V/3.3V	211	-4	caBGA	256	COM
LCMXO2280C-5B256C	2280	1.8V/2.5V/3.3V	211	-5	caBGA	256	COM
LCMXO2280C-3FT256C	2280	1.8V/2.5V/3.3V	211	-3	ftBGA	256	COM
LCMXO2280C-4FT256C	2280	1.8V/2.5V/3.3V	211	-4	ftBGA	256	COM
LCMXO2280C-5FT256C	2280	1.8V/2.5V/3.3V	211	-5	ftBGA	256	COM
LCMXO2280C-3FT324C	2280	1.8V/2.5V/3.3V	271	-3	ftBGA	324	COM
LCMXO2280C-4FT324C	2280	1.8V/2.5V/3.3V	271	-4	ftBGA	324	COM
LCMXO2280C-5FT324C	2280	1.8V/2.5V/3.3V	271	-5	ftBGA	324	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO256E-3T100C	256	1.2V	78	-3	TQFP	100	COM
LCMXO256E-4T100C	256	1.2V	78	-4	TQFP	100	COM
LCMXO256E-5T100C	256	1.2V	78	-5	TQFP	100	COM
LCMXO256E-3M100C	256	1.2V	78	-3	csBGA	100	COM
LCMXO256E-4M100C	256	1.2V	78	-4	csBGA	100	COM
LCMXO256E-5M100C	256	1.2V	78	-5	csBGA	100	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO640E-3T100C	640	1.2V	74	-3	TQFP	100	COM
LCMXO640E-4T100C	640	1.2V	74	-4	TQFP	100	COM
LCMXO640E-5T100C	640	1.2V	74	-5	TQFP	100	COM
LCMXO640E-3M100C	640	1.2V	74	-3	csBGA	100	COM
LCMXO640E-4M100C	640	1.2V	74	-4	csBGA	100	COM
LCMXO640E-5M100C	640	1.2V	74	-5	csBGA	100	COM
LCMXO640E-3T144C	640	1.2V	113	-3	TQFP	144	COM
LCMXO640E-4T144C	640	1.2V	113	-4	TQFP	144	COM
LCMXO640E-5T144C	640	1.2V	113	-5	TQFP	144	COM
LCMXO640E-3M132C	640	1.2V	101	-3	csBGA	132	COM
LCMXO640E-4M132C	640	1.2V	101	-4	csBGA	132	COM
LCMXO640E-5M132C	640	1.2V	101	-5	csBGA	132	COM
LCMXO640E-3B256C	640	1.2V	159	-3	caBGA	256	COM
LCMXO640E-4B256C	640	1.2V	159	-4	caBGA	256	COM
LCMXO640E-5B256C	640	1.2V	159	-5	caBGA	256	COM
LCMXO640E-3FT256C	640	1.2V	159	-3	ftBGA	256	COM
LCMXO640E-4FT256C	640	1.2V	159	-4	ftBGA	256	COM
LCMXO640E-5FT256C	640	1.2V	159	-5	ftBGA	256	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO256E-3T100I	256	1.2V	78	-3	TQFP	100	IND
LCMXO256E-4T100I	256	1.2V	78	-4	TQFP	100	IND
LCMXO256E-3M100I	256	1.2V	78	-3	csBGA	100	IND
LCMXO256E-4M100I	256	1.2V	78	-4	csBGA	100	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO640E-3T100I	640	1.2V	74	-3	TQFP	100	IND
LCMXO640E-4T100I	640	1.2V	74	-4	TQFP	100	IND
LCMXO640E-3M100I	640	1.2V	74	-3	csBGA	100	IND
LCMXO640E-4M100I	640	1.2V	74	-4	csBGA	100	IND
LCMXO640E-3T144I	640	1.2V	113	-3	TQFP	144	IND
LCMXO640E-4T144I	640	1.2V	113	-4	TQFP	144	IND
LCMXO640E-3M132I	640	1.2V	101	-3	csBGA	132	IND
LCMXO640E-4M132I	640	1.2V	101	-4	csBGA	132	IND
LCMXO640E-3B256I	640	1.2V	159	-3	caBGA	256	IND
LCMXO640E-4B256I	640	1.2V	159	-4	caBGA	256	IND
LCMXO640E-3FT256I	640	1.2V	159	-3	ftBGA	256	IND
LCMXO640E-4FT256I	640	1.2V	159	-4	ftBGA	256	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO1200E-3T100I	1200	1.2V	73	-3	TQFP	100	IND
LCMXO1200E-4T100I	1200	1.2V	73	-4	TQFP	100	IND
LCMXO1200E-3T144I	1200	1.2V	113	-3	TQFP	144	IND
LCMXO1200E-4T144I	1200	1.2V	113	-4	TQFP	144	IND
LCMXO1200E-3M132I	1200	1.2V	101	-3	csBGA	132	IND
LCMXO1200E-4M132I	1200	1.2V	101	-4	csBGA	132	IND
LCMXO1200E-3B256I	1200	1.2V	211	-3	caBGA	256	IND
LCMXO1200E-4B256I	1200	1.2V	211	-4	caBGA	256	IND
LCMXO1200E-3FT256I	1200	1.2V	211	-3	ftBGA	256	IND
LCMXO1200E-4FT256I	1200	1.2V	211	-4	ftBGA	256	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO2280E-3T100I	2280	1.2V	73	-3	TQFP	100	IND
LCMXO2280E-4T100I	2280	1.2V	73	-4	TQFP	100	IND
LCMXO2280E-3T144I	2280	1.2V	113	-3	TQFP	144	IND
LCMXO2280E-4T144I	2280	1.2V	113	-4	TQFP	144	IND
LCMXO2280E-3M132I	2280	1.2V	101	-3	csBGA	132	IND
LCMXO2280E-4M132I	2280	1.2V	101	-4	csBGA	132	IND
LCMXO2280E-3B256I	2280	1.2V	211	-3	caBGA	256	IND
LCMXO2280E-4B256I	2280	1.2V	211	-4	caBGA	256	IND
LCMXO2280E-3FT256I	2280	1.2V	211	-3	ftBGA	256	IND
LCMXO2280E-4FT256I	2280	1.2V	211	-4	ftBGA	256	IND
LCMXO2280E-3FT324I	2280	1.2V	271	-3	ftBGA	324	IND
LCMXO2280E-4FT324I	2280	1.2V	271	-4	ftBGA	324	IND

Revision History

Date	Version	Section	Change Summary
February 2005	01.0	—	Initial release.
October 2005	01.1	Introduction	Distributed RAM information in family table updated. Added footnote 1 - fpBGA packaging to the family selection guide.
		Architecture	sysIO Buffer section updated.
			Hot Socketing section updated.
			Sleep Mode section updated.
			SLEEP Pin Characteristics section updated.
			Oscillator section updated.
			Security section updated.
		DC and Switching Characteristics	Recommended Operating Conditions table updated.
			DC Electrical Characteristics table updated.
			Supply Current (Sleep Mode) table added with LCMXO256/640 data.
			Supply Current (Standby) table updated with LCMXO256/640 data.
			Initialization Supply Current table updated with LCMXO256/640 data.
			Programming and Erase Flash Supply Current table updated with LCMXO256/640 data.
			Register-to-Register Performance table updated (rev. A 0.16).
			External Switching Characteristics table updated (rev. A 0.16).
			Internal Timing Parameter table updated (rev. A 0.16).
			Family Timing Adders updated (rev. A 0.16).
			sysCLOCK Timing updated (rev. A 0.16).
			MachXO "C" Sleep Mode Timing updated (A 0.16).
			JTAG Port Timing Specification updated (rev. A 0.16).
		Pinout Information	SLEEPIN description updated.
			Pin Information Summary updated.
			Power Supply and NC Connection table has been updated.
			Logic Signal Connection section has been updated to include all devices/packages.
		Ordering Information	Part Number Description section has been updated.
			Ordering Part Number section has been updated (added LCMXO256C/LCMXO640C "4W").
		Supplemental Information	MachXO Density Migration Technical Note (TN1097) added.
November 2005	01.2	Pinout Information	Added "Power Supply and NC Connections" summary information for LCMXO1200 and LCMXO2280 in 100 TQFP package.
December 2005	01.3	DC and Switching Characteristics	Supply Current (Standby) table updated with LCMXO1200/2280 data.
		Ordering Information	Ordering Part Number section updated (added LCMXO2280C "4W").
April 2006	02.0	Introduction	Introduction paragraphs updated.
		Architecture	Architecture Overview paragraphs updated.

Date	Version	Section	Change Summary
November 2006	02.3	DC and Switching Characteristics	Corrections to MachXO “C” Sleep Mode Timing table - value for $t_{WSLEEPN}$ (400ns) changed from max. to min. Value for t_{WAWAKE} (100ns) changed from min. to max.
			Added Flash Download Time table.
December 2006	02.4	Architecture	EBR Asynchronous Reset section added.
		Pinout Information	Power Supply and NC table; Pin/Ball orientation footnotes added.
February 2007	02.5	Architecture	Updated EBR Asynchronous Reset section.
August 2007	02.6	DC and Switching Characteristics	Updated sysIO Single-Ended DC Electrical Characteristics table.
November 2007	02.7	DC and Switching Characteristics	Added JTAG Port Timing Waveforms diagram.
		Pinout Information	Added Thermal Management text section.
		Supplemental Information	Updated title list.
June 2009	02.8	Introduction	Added 0.8-mm 256-pin caBGA package to MachXO Family Selection Guide table.
		Pinout Information	Added Logic Signal Connections table for 0.8-mm 256-pin caBGA package.
		Ordering Information	Updated Part Number Description diagram and Ordering Part Number tables with 0.8-mm 256-pin caBGA package information.
July 2010	02.9	DC and Switching Characteristics	Updated sysCLOCK PLL Timing table.
June 2013	03.0	All	Updated document with new corporate logo.
		Architecture	Architecture Overview – Added information on the state of the register on power up and after configuration.
		DC and Switching Characteristics	MachXO1200 and MachXO2280 Hot Socketing Specifications table – Removed footnote 4.
			Added MachXO Programming/Erase Specifications table.